

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Micron Technology, Inc.	10/03/2008
RECEIVING PARTY DATA	
Name:	Aptina Imaging Corporation
Street Address:	c/o Citco Trustees (Cayman) Limited
Internal Address:	Regatta Office Park, West Bay Road
City:	Grand Cayman
State/Country:	CAYMAN ISLANDS
Postal Code:	Y1-1205
PROPERTY NUMBERS Total: 3	
Property Type	Number
Patent Number:	7397066
Application Number:	11488848
Application Number:	12155645
CORRESPONDENCE DATA	
Fax Number:	(202)420-2201
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	202 420-2200
Email:	JoelT@dicksteinshapiro.com
Correspondent Name:	Dickstein Shapiro LLP
Address Line 1:	1825 Eye Street, NW
Address Line 4:	Washington, DC, DISTRICT OF COLUMBIA 20006
ATTORNEY DOCKET NUMBER:	M4065.1307/P1307
NAME OF SUBMITTER:	Teresa Joel
Total Attachments: 7	

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PATENT ASSIGNMENT AGREEMENT

1. Definitions

(a) "Agreement" shall mean this Patent Assignment Agreement.

(b) "Assignee" shall mean **Aptina Imaging Corporation**, a Cayman Islands corporation with offices at c/o Citco Trustees (Cayman) Limited, Regatta Office Park, West Bay Road, Grand Cayman, Y1-1205, Cayman Islands.

(c) "Assignor" shall mean **Micron Technology, Inc.**, a Delaware corporation with offices at 8000 South Federal Way, Boise, ID 83707.

(d) "Effective Date" shall mean October 3, 2008.

(e)



(f)



(g) "Imaging Patents" shall mean those patents identified in ATTACHMENT "A" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(h) "Imaging Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "B" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(i) "Semiconductor Patents" shall mean those patents identified in ATTACHMENT "D" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(j) "Semiconductor Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "E" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(k) [REDACTED]

2. [REDACTED]

(a) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Imaging Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Imaging Patents to Assignee and to record assignment of the Imaging Patents to Assignee.

(b) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Imaging Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Imaging Patent Applications to Assignee.

(c) [REDACTED]

(d) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, and subject further to the restrictions on the Semiconductor Patents set out below, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Semiconductor Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Semiconductor Patents to Assignee and to record assignment of the Semiconductor Patents to Assignee.

(e) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, [REDACTED], Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Semiconductor Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Semiconductor Patent Applications to Assignee.

(1)

[REDACTED]

[REDACTED]

[REDACTED]

3 [REDACTED]

[REDACTED]

4. [REDACTED]

[REDACTED]

5. [REDACTED]

[REDACTED]

[REDACTED]

6. [REDACTED]

[REDACTED]

7. General

This Agreement shall be effective as of the Effective Date hereof and shall be binding on the respective heirs, assigns, representatives, and successors of Assignor and of Assignee.

[the rest of this page intentionally left blank]

Agreed to by:

Micron Technology, Inc.

Signed: _____

Date: 9/26/08, 2008

Notarization

State of Idaho
County of Ada

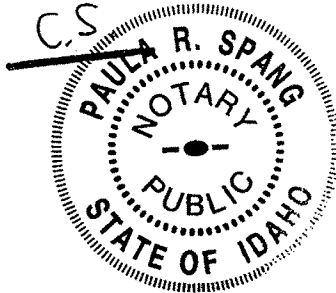
On 9/26/08, before me, Paula R. Spang, personally appeared the above-named Steven B. Appleton

who executed this Assignment in my presence and acknowledged to me that he did so of his own free will and in his authorized capacity for the purposes set forth herein.

Signed: _____

My commission expires: 8/12/11

REVIEWED
MTI LEGAL



Agreed to by:

Aptina Imaging Corporation

Signed: _____

Date: 9/26/08, 2008

Notarization

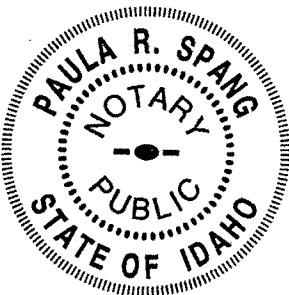
State of Idaho
County of Ada

On 9/26/08, before me, Paula R. Spang, personally appeared the above-named Thomas L. Lewis, Jr.

who executed this Assignment in my presence and acknowledged to me that he did so of his own free will and in his authorized capacity for the purposes set forth herein.

Signed: _____

My commission expires: 8/12/11



[Signature page to the Patent Assignment Agreement]

ATTACHMENT "B"



Aptina Applications

FILE NUMBER	TITLE	STATUS	COUNTRY NAME	APPLICATION NUMBER	DATE FILED
	VOLTAGE				
2004-0572.01/US	METHODS FOR MANUFACTURING MICROELECTRONIC IMAGERS	Pending	United States of America	1148848	Jul 18, 2006
2004-0572.02/US	MICROELECTRONIC IMAGERS WITH CURVED IMAGE SENSORS AND METHODS FOR MANUFACTURING MICROELECTRONIC IMAGERS	Pending	United States of America		Jun 6, 2008
2004-0575.00/US	CLAMPED CAPACITOR READOUT NOISE REJECTION CIRCUIT FOR IMAGERS	Pending	United States of America	11064503	Feb 24, 2005
2004-0621.00/US	PHASE SHIFT TRANSPARENT STRUCTURES FOR IMAGING DEVICES	Pending	United States of America	11134315	May 23, 2005
2004-0630.00/CN	ISOLATION STRUCTURE AND PROCESS FOR CMOS IMAGERS	Pending	China	2006800181392	May 24, 2006
2004-0630.00/EP	ISOLATION STRUCTURE AND PROCESS FOR CMOS IMAGERS	Pending	European Patent Office	067709758	May 24, 2006
2004-0630.00/JP	ISOLATION STRUCTURE AND PROCESS FOR CMOS IMAGERS	Pending	Japan	2008513633	May 24, 2006
2004-0630.00/KR	ISOLATION STRUCTURE AND PROCESS FOR CMOS IMAGERS	Pending	Republic of Korea	1020077029990	May 24, 2006
2004-0630.00/PC	ISOLATION STRUCTURE AND PROCESS FOR CMOS IMAGERS	Completed	PCT	PCTUS200619954	May 24, 2006
2004-0630.00/SG	ISOLATION STRUCTURE AND PROCESS FOR CMOS IMAGERS	Pending	Singapore	2007173768	May 24, 2006
2004-0630.00/TW	ISOLATION STRUCTURE AND PROCESS FOR CMOS IMAGERS	Pending	Taiwan R.O.C.	095118438	May 24, 2006
2004-0630.00/US	ISOLATION STRUCTURE AND PROCESS FOR CMOS	Allowed	United States of America	11135517	May 24, 2005

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